- **Meets or Exceeds the Requirements of ANSI Standard EIA/TIA-422-B and ITU Recommendation V.11**
- **Designed to Operate up to 20 Mbaud**
- **3-State TTL Compatible**
- **Single 5-V Supply Operation**
- **High Output Impedance in Power-Off Condition**
- **Complementary Output-Enable Inputs**
- **Improved Replacement for the AM26LS31**

D OR N PACKAGE
(TOP VIEW)

1A	1	16	V_{CC}
1Y	2	15	4A
1Z	3	14	4Y
G	4	13	4Z
2Z	5	12	$\overline{G}$
2Y	6	11	3Z
2A	7	10	3Y
GND	8	9	3A
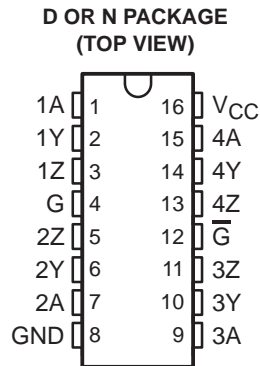
description

The four differential line drivers are designed for data transmission over twisted-pair or parallel-wire transmission lines. They meet the requirements of ANSI Standard EIA/TIA-422-B and ITU Recommendations V.11 and are compatible with 3-state TTL circuits. Advanced low-power Schottky technology provides high speed without the usual power penalties. Standby supply current is typically only 26 mA, while typical propagation delay time is less than 10 ns.

High-impedance inputs maintain low input currents, less than 1 μA for a high level and less than 100 μA for a low level. Complementary output-enable inputs (G and $\overline{G}$) allow these devices to be enabled at either a high input level or low input level. The SN75ALS192 is capable of data rates in excess of 20 Mbit/s and is designed to operate with the SN75ALS193 quadruple line receiver.

The SN75ALS192 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE
(each driver)

INPUT A	ENABLES		OUTPUTS	
	G	$\overline{G}$	Y	Z
H	H	X	H	L
L	H	X	L	H
H	X	L	H	L
L	X	L	L	H
X	L	H	Z	Z

H = high level, L = low level, X = irrelevant,
Z = high impedance (off)

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

SN75ALS192
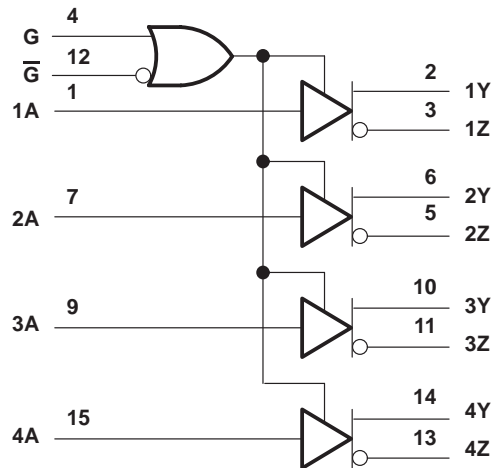# QUADRUPLE DIFFERENTIAL LINE DRIVER

SLLS007D – JULY 1985 – REVISED APRIL 1998
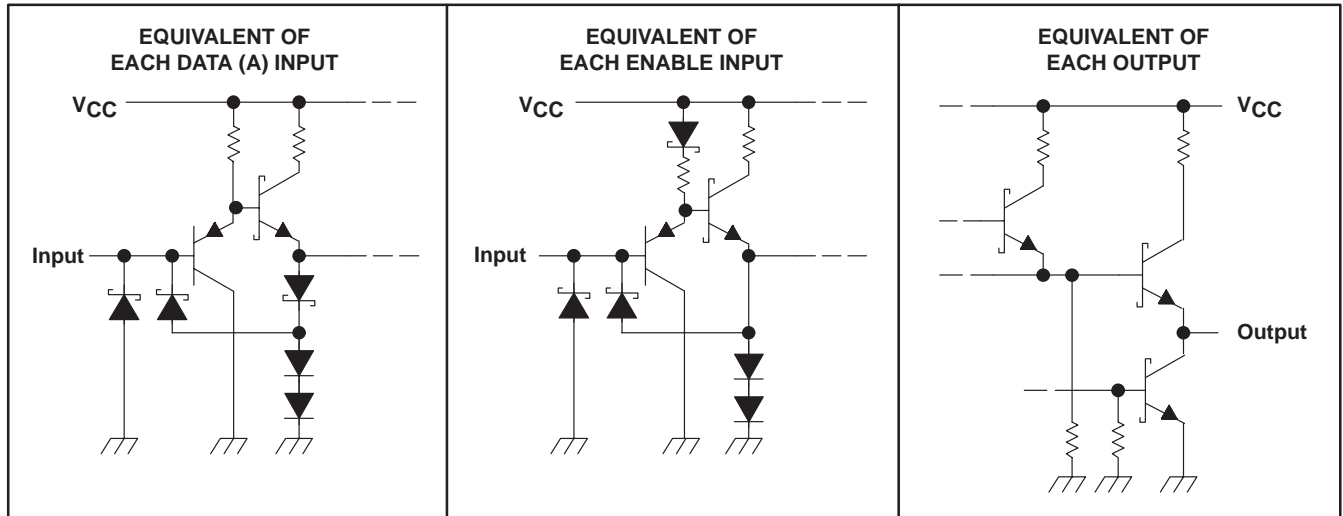
logic symbol†
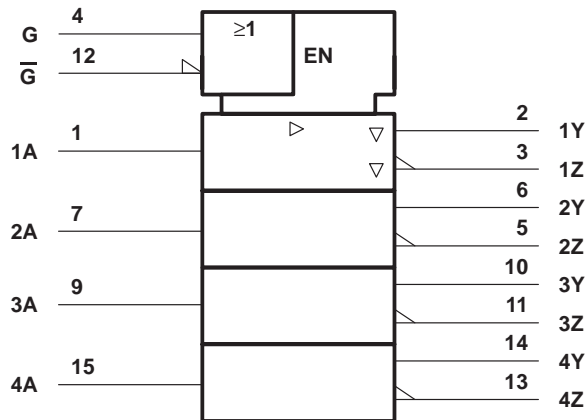
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)

schematics of inputs and outputs

EQUIVALENT OF EACH DATA (A) INPUT

EQUIVALENT OF EACH ENABLE INPUT

EQUIVALENT OF EACH OUTPUT

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . 7 V
Input voltage, V_I . . . . 7 V
Off-state output voltage . . . . 6 V
Continuous total dissipation . . . . See Dissipation Rating Table
Storage temperature range, T_{stg} . . . . −65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . 260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and
functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not
implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1: All voltage values except differential output voltage, V_{OD}, are with respect to network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D	950 mW	7.6 mW/°C	608 mW	N/A
N	1150 mW	9.2 mW/°C	736 mW	N/A

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.75	5	5.25	V
High level input voltage, V_{IH}	2			V
Low-level input voltage, V_{IL}			0.8	V
High-level output current, I_{OH}			−20	mA
Low-level output current, I_{OL}			20	mA
Operating free-air temperature, T_A	0		70	°C

SN75ALS192
QUADRUPLE DIFFERENTIAL LINE DRIVER

SLLS007D – JULY 1985 – REVISED APRIL 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
V_{IK}	Input clamp voltage	V_{CC} = MIN,	I_I = –18 mA			–1.5	V
V_{OH}	High-level output voltage	V_{CC} = MIN,	I_{OH} = –20 mA	2.5			V
V_{OL}	Low-level output voltage	V_{CC} = MIN,	I_{OL} = 20 mA			0.5	V
V_O	Output voltage	V_{CC} = MAX,	I_O = 0	0		6	V
$|V_{OD1}|$	Differential output voltage	V_{CC} = MIN,	I_O = 0	1.5		6	V
$|V_{OD2}|$	Differential output voltage	R_L = 100 Ω,	See Figure 1	1/2 V_{OD1} or 2§			V
$\Delta|V_{OD}|$	Change in magnitude of differential output voltage¶	R_L = 100 Ω,	See Figure 1			±0.2	V
V_{OC}	Common-mode output voltage#	R_L = 100 Ω,	See Figure 1			±3	V
$\Delta|V_{OC}|$	Change in magnitude of common-mode output voltage¶	R_L = 100 Ω,	See Figure 1			±0.2	V
I_O	Output current with power off	V_{CC} = 0	V_O = 6 V			100	µA
			V_O = –0.25 V			–100	
I_{OZ}	Off-state (high-impedance state) output current	V_{CC} = MAX	V_O = 0.5 V			–20	µA
			V_O = 2.5 V			20	
I_I	Input current at maximum input voltage	V_{CC} = MAX,	V_I = 7 V			100	µA
I_{IH}	High-level input current	V_{CC} = MAX,	V_I = 2.7 V			20	µA
I_{IL}	Low-level input current	V_{CC} = MAX,	V_I = 0.4 V			–200	µA
I_{OS}	Short-circuit output current‖	V_{CC} = MAX		–30		–150	mA
I_{CC}	Supply current (all drivers)	V_{CC} = MAX,	All outputs disabled		26	45	mA

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡ All typical values are at V_{CC} = 5 V and T_A = 25°C.
§ The minimum V_{OD2} with a 100-Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.
¶ $|V_{OD}|$ and $|V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input is changed from a high level to a low level.
# In ANSI Standard EIA/TIA-422-B, V_{OC}, which is the average of the two output voltages with respect to ground, is called output offset voltage, V_{OS}.
‖ Not more than one output should be shorted at a time, and duration of the short circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see Figure 2)

	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high-level output	S1 and S2 open,	C_L = 30 pF		6	13	ns
t_{PHL}	Propagation delay time, high-to-low-level output	S1 and S2 open,	C_L = 30 pF		9	14	ns
	Output-to-output skew	S1 and S2 open,	C_L = 30 pF		3	6	ns
t_{PZH}	Output enable time to high level	S1 open and S2 closed			11	15	ns
t_{PZL}	Output enable time to low level	S1 closed and S2 open			16	20	ns
t_{PHZ}	Output disable time from high level	S1 open and S2 closed,	C_L = 10 pF		8	15	ns
t_{PLZ}	Output disable time from low level	S1 and S2 closed,	C_L = 10 pF		18	20	ns

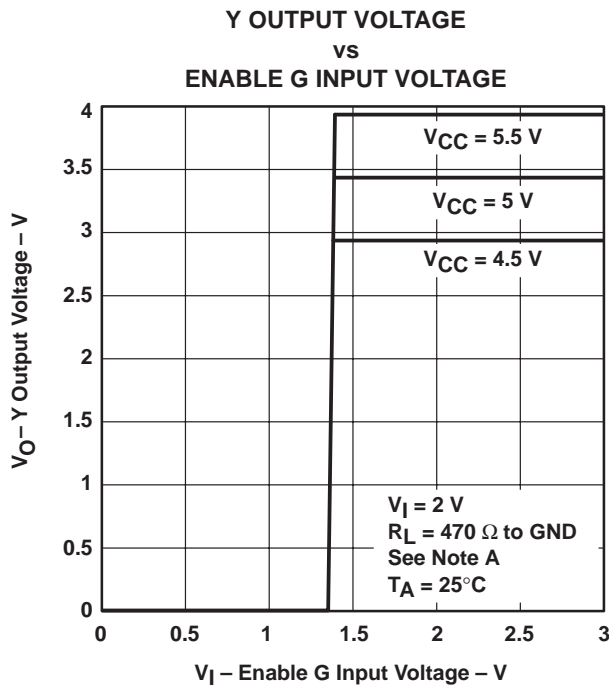![Texas Instruments logo]

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PARAMETER MEASUREMENT INFORMATION
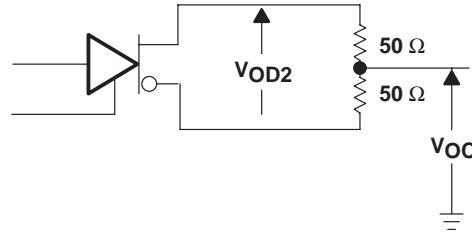
Figure 1. Differential and Common-Mode Output Voltages

PROPAGATION DELAY TIMES AND SKEW

ENABLE AND DISABLE TIMES

VOLTAGE WAVEFORMS

TEST CIRCUIT
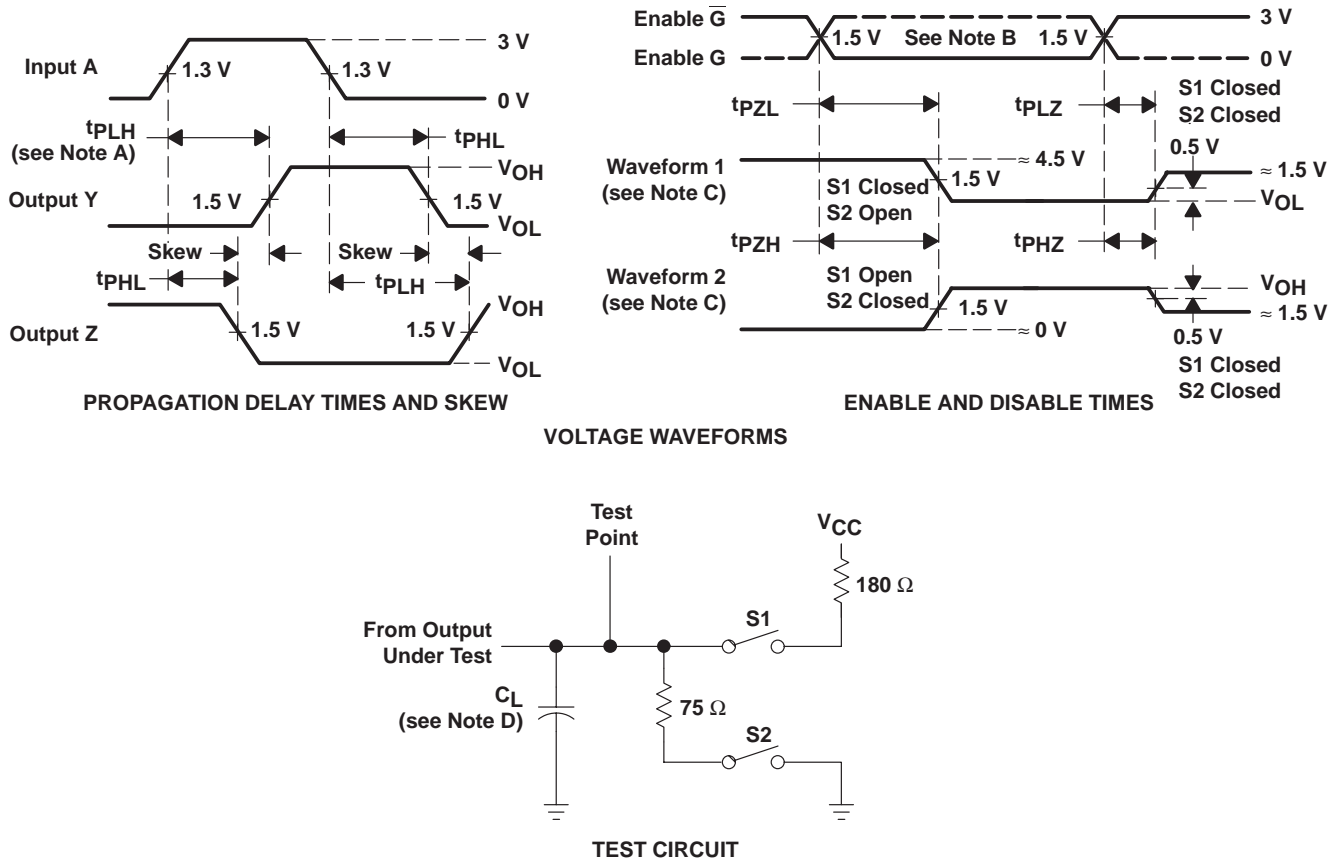
NOTES: A. When measuring propagation delay times and skew, switches S1 and S2 are open.
   B. Each enable is tested separately.
   C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
      Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
   D. C_L includes probe and jig capacitance.
   E. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O ≈ 50 Ω, t_r ≤ 15 ns, and t_f ≤ 6 ns.

Figure 2. Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS†

Y OUTPUT VOLTAGE
vs
DATA INPUT VOLTAGE

Figure 3

Y OUTPUT VOLTAGE
vs
DATA INPUT VOLTAGE
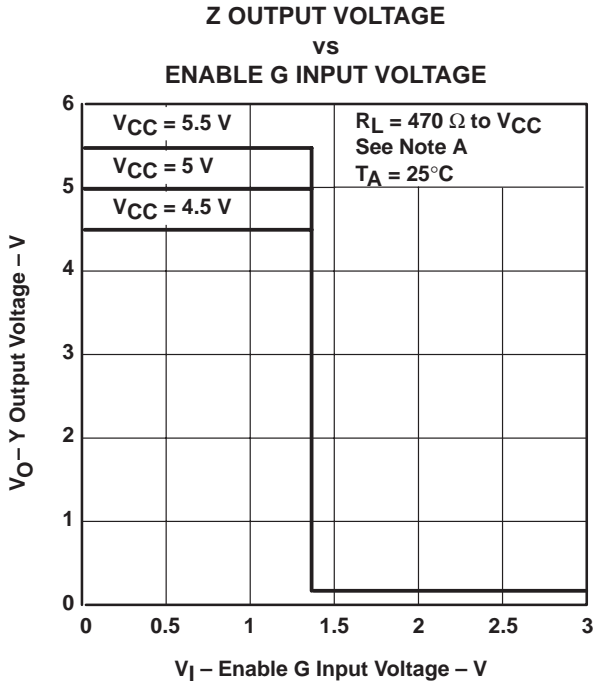

Figure 4

Y OUTPUT VOLTAGE
vs
ENABLE G INPUT VOLTAGE

NOTE A: The A input is connected to V_{CC} during the testing of the Y outputs and to ground during the testing of the Z outputs.
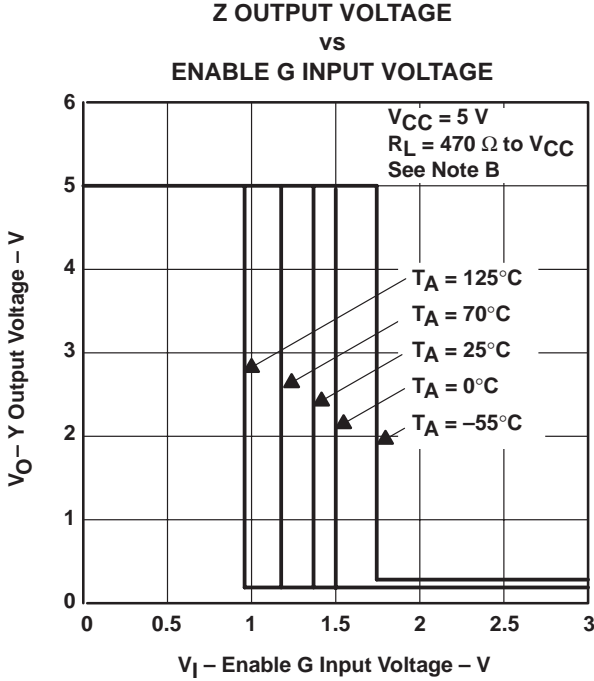
Figure 5

Y OUTPUT VOLTAGE
vs
ENABLE G INPUT VOLTAGE

NOTE A: The A input is connected to V_{CC} during the testing of the Y outputs and to ground during the testing of the Z outputs.
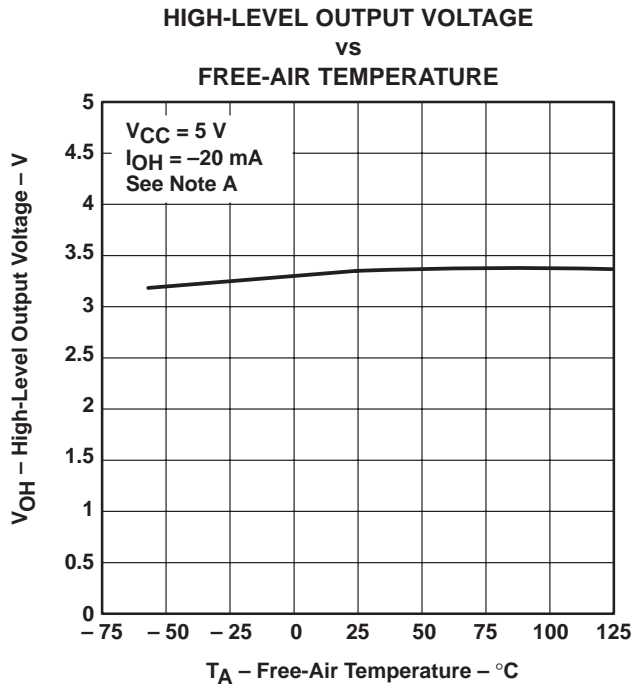
Figure 6

† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

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TYPICAL CHARACTERISTICS†

Z OUTPUT VOLTAGE
vs
ENABLE G INPUT VOLTAGE

NOTE A: The A input is connected to V_{CC} during the testing of the Y outputs and to ground during the testing of the Z outputs.
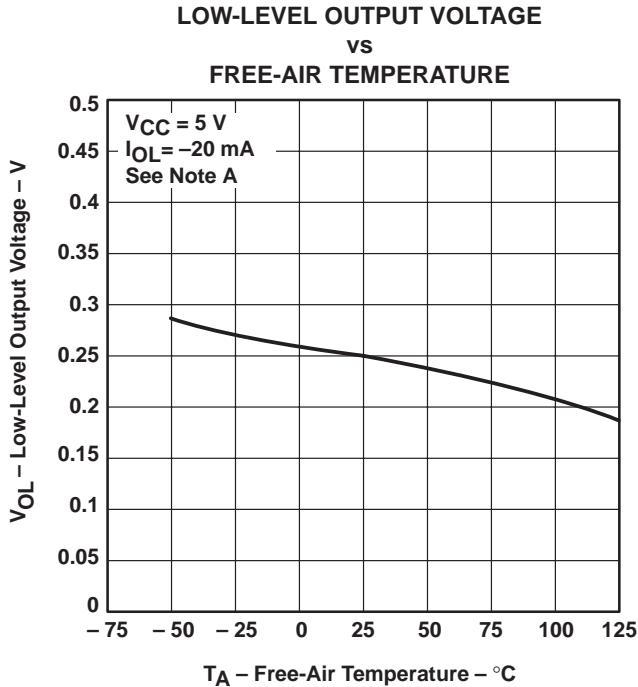
Figure 7

Z OUTPUT VOLTAGE
vs
ENABLE G INPUT VOLTAGE

NOTE B: The A input is connected to GND during the testing of the Y outputs and to V_{CC} during the testing of the Z outputs.

Figure 8

† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

TYPICAL CHARACTERISTICS†

HIGH-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

V_{CC} = 5 V
I_{OH} = −20 mA
See Note A

V_{OH} – High-Level Output Voltage – V

T_A – Free-Air Temperature – °C

NOTE A: The A input is connected to V_{CC} during the testing of the Y outputs and to ground during the testing of the Z outputs.

Figure 9

HIGH-LEVEL OUTPUT VOLTAGE
vs
OUTPUT CURRENT

See Note A
T_A = 25°C

V_{CC} = 5.5 V
V_{CC} = 5 V
V_{CC} = 4.5 V

V_{OH} – High-Level Output Voltage – V

I_{OH} – High-Level Output Current – mA
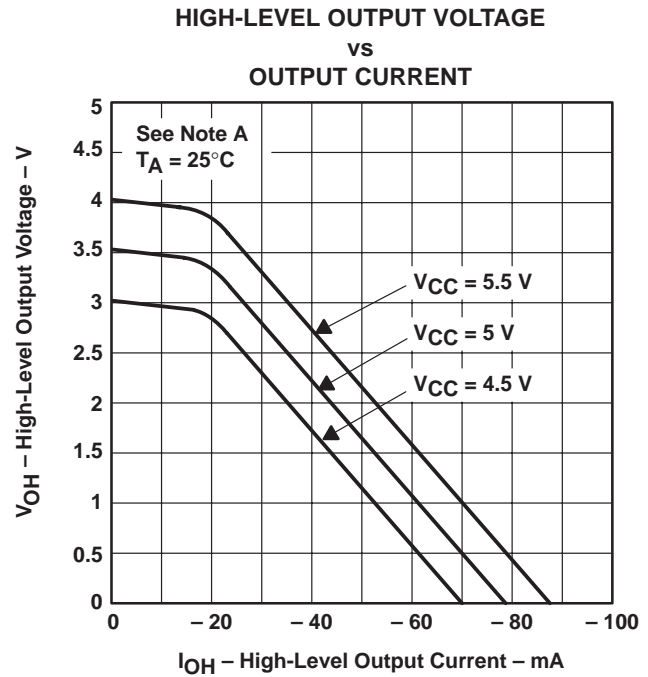
NOTE A: The A input is connected to V_{CC} during the testing of the Y outputs and to ground during the testing of the Z outputs.
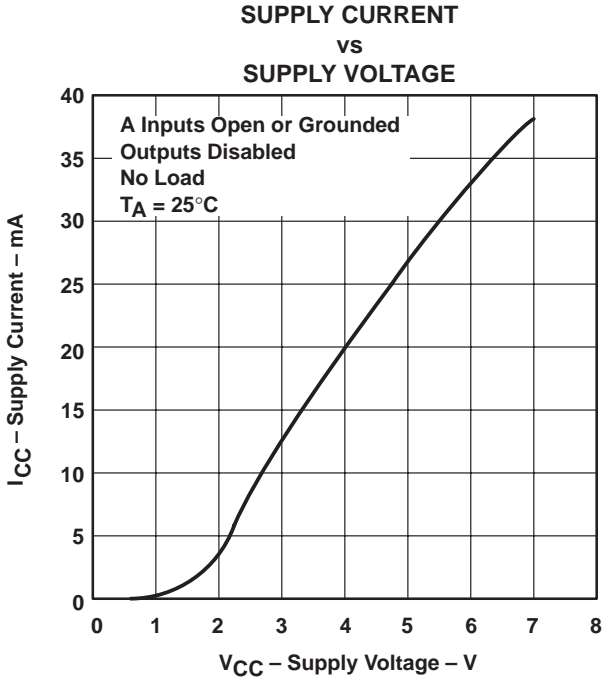
Figure 10

† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

TYPICAL CHARACTERISTICS†

LOW-LEVEL OUTPUT VOLTAGE
vs
FREE-AIR TEMPERATURE

NOTE A: The A input is connected to GND during the testing of the
Y outputs and to V_{CC} during the testing of the Z outputs.

Figure 11

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

NOTE A: The A input is connected to GND during the testing of the
Y outputs and to V_{CC} during the testing of the Z outputs.

Figure 12

SUPPLY CURRENT
vs
SUPPLY VOLTAGE

Figure 13

SUPPLY CURRENT
vs
SUPPLY VOLTAGE
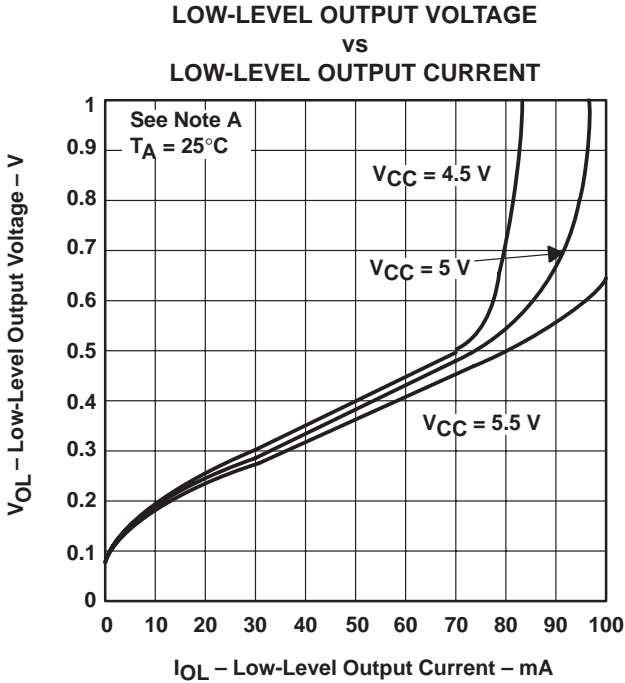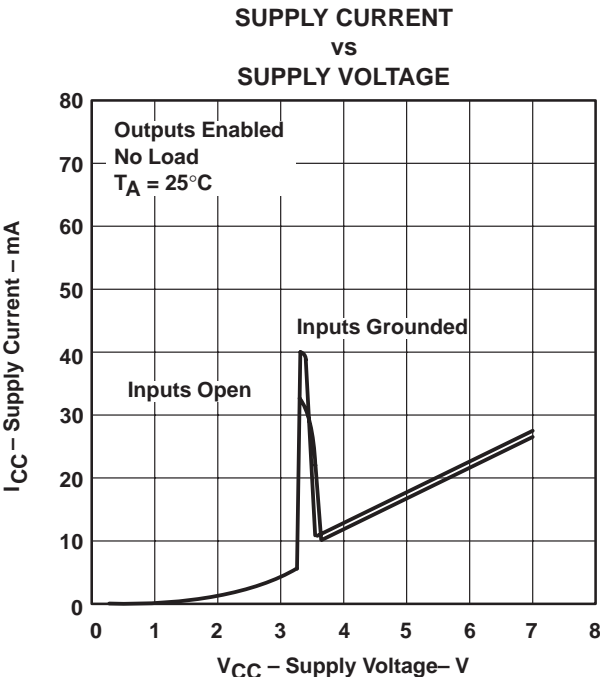
Figure 14

† Operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied.

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TYPICAL CHARACTERISTICS

SUPPLY CURRENT
vs
FREQUENCY

V$_{CC}$ = 5 V
Input = 0 to 3 V
Duty Cycle = 50%
C$_L$ = 30 pF to All Outputs
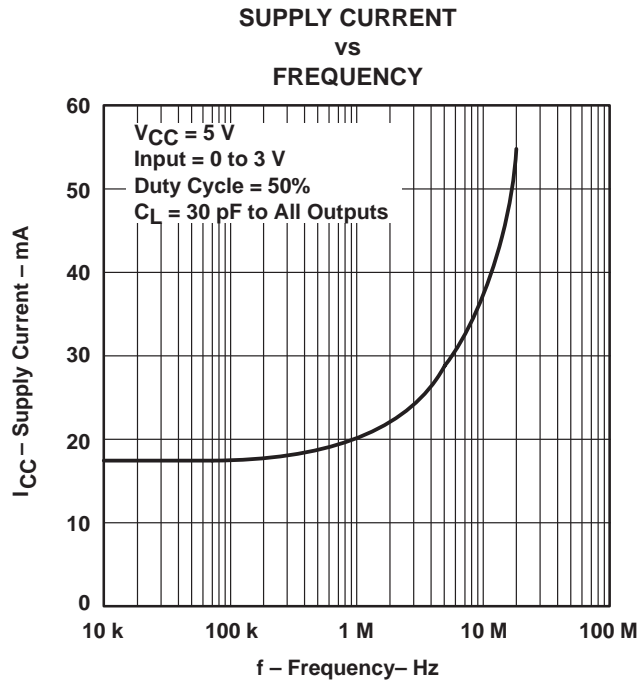
Figure 15

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN75ALS192D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS192	Samples
SN75ALS192DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS192	Samples
SN75ALS192DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS192	Samples
SN75ALS192DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS192	Samples
SN75ALS192DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS192	Samples
SN75ALS192DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS192	Samples
SN75ALS192N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75ALS192N	Samples
SN75ALS192NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN75ALS192N	Samples
SN75ALS192NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS192	Samples
SN75ALS192NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS192	Samples
SN75ALS192NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	75ALS192	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF SN75ALS192 :

● Military: SN55ALS192

NOTE: Qualified Version Definitions:

    ● Military - QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS192DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS192DR	SOIC	D	16	2500	333.2	345.9	28.6

N (R–PDIP–T**)
16 PINS SHOWN

PLASTIC DUAL–IN–LINE PACKAGE

	PINS **	14	16	18	20
DIM					
A MAX		0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN		0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION		AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14)

0.045 (1,14) / 0.030 (0,76)

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

0.010 (0,25) M

14/18 Pin Only
20 Pin vendor option

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E   12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
         D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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D (R−PDSO−G16) PLASTIC SMALL OUTLINE

0.394 (10,00)
0.386 (9,80)
⚠C

16 9

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) ⚠D

1 8

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

Pin 1
Index Area

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

Gauge Plane

0.004 (0,10)

Seating Plane

0.010 (0,25) 0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−6/M 06/11

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
⚠C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
⚠D Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS−012 variation AC.

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D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

14x1,27

16x0,55

14x1,27

16x1,50

5,40

5.40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

1,55

Example
Solder Mask Opening
(See Note E)

0,07

All Around

4211283−4/E 08/12

NOTES: A. All linear dimensions are in millimeters.
          B. This drawing is subject to change without notice.
          C. Publication IPC−7351 is recommended for alternate designs.
          D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
          E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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MECHANICAL DATA

DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
        B. This drawing is subject to change without notice.
        C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

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Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
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